



Material Content Data Sheet



Sales Product Name		BSC032N04LS		Issued		19. July 2018		
MA#		MA001075706						
Package		PG-TDSON-8-6		Weight*		118.22 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.447	0.38	0.38	3784	3784
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		320	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		96	
	non noble metal	copper	7440-50-8	37.762	31.94	31.98	319409	319825
wire	noble metal	gold	7440-57-5	0.045	0.04	0.04	383	383
encapsulation	organic material	carbon black	1333-86-4	0.088	0.07		744	
	plastics	epoxy resin	-	6.243	5.28		52804	
	inorganic material	silicondioxide	60676-86-0	37.632	31.83	37.18	318312	371860
leadfinish	non noble metal	tin	7440-31-5	1.452	1.23	1.23	12279	12279
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1400	1400
solder	noble metal	silver	7440-22-4	0.017	0.01		145	
	non noble metal	tin	7440-31-5	0.014	0.01		116	
	non noble metal	lead	7439-92-1	0.654	0.55	0.57	5529	5790
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		96	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		29	
	non noble metal	copper	7440-50-8	11.320	9.58	9.59	95752	95877
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		189	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		57	
	non noble metal	copper	7440-50-8	22.292	18.86	18.89	188556	188802
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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